

ABSTRACT OF THE DISCLOSURE

In a separate process from a boring process, the prealignment is performed beforehand on the circuit board, employing an alignment device, to create the positional data indicating the position of boring the hole in a pattern within the circuit board. In the boring process, the circuit board is carried into the working apparatus. The panel alignment is made on the circuit board. The positional data for positioning the circuit board on a table of the working apparatus is created.

The synthesis of the positional data created by the prealignment and the positional data created by the panel alignment is performed to calculate the boring position of the circuit board on the table. The hole is bored at the calculated position in the circuit board, employing a boring machine of the working apparatus. Thereafter, the circuit board is carried out from the working apparatus.